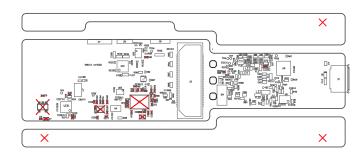


- ZZI minstall label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic. ZZ2 minse assemblies are ESD sensitive, ESD precautions shall be observed. ZZ3 minses assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

- 225 I These assemblies must comply with workmanship standards IPC-AF-010 Class 2, unless otherwise specified.
  225.I ECut the thermal padCPart Number#BPDUDS-0.125-AC-0916) for the shape and size of the inner surface of the heatsink(Part Number#BPDUDS-0.125-AC-0916) for the shape and size of the inner surface of the heatsink onto the PCB bottom side (Opposite side of ADD device). How the testink with break-away area in the PCB and press the heatsink onto the PCB slightly so as thermal pad is spread all over the area

## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PROCO91	REV: F	SUN REV	: Not In VersionControl
M5 Assembly Top	TID #: N/A			
PLOT NAME = Top Assembly Drawing	GENERATED : 11-11-2	2020 20: 20: 07		TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PROCO91 REV: F	SVN REV: Not In VersionControl	
	TID #: N/A M6 Assembly Bottom		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11-11-2020 20:20:	07 TEXAS INSTRUMENTS	